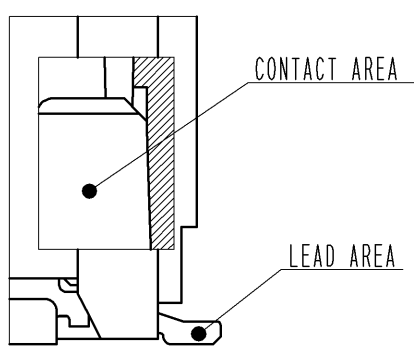
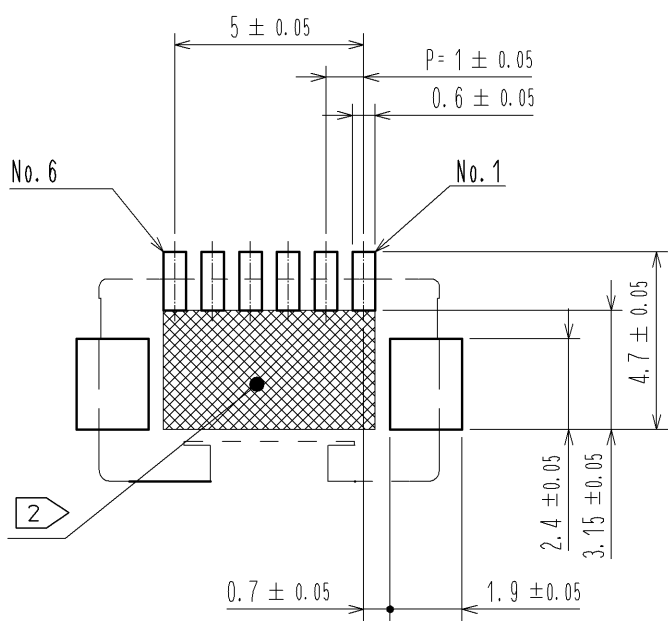


A (10 : 1)

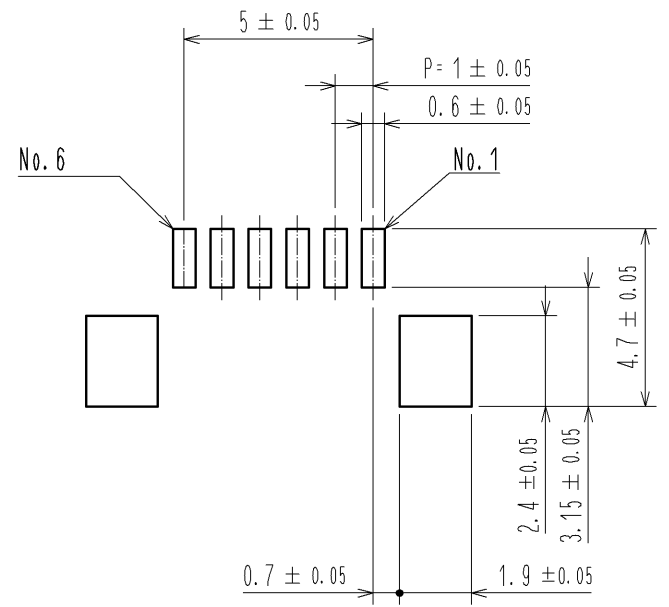


RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

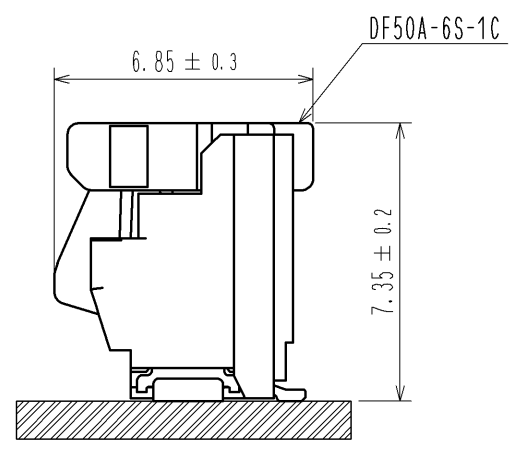
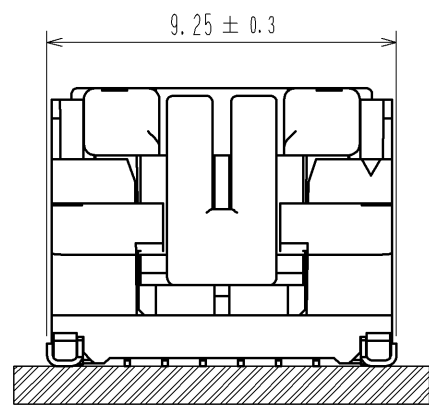


RECOMMENDED METAL MASK (FREE)

THICKNESS : 0.1mm
OPEN AREA RATIO : 100%



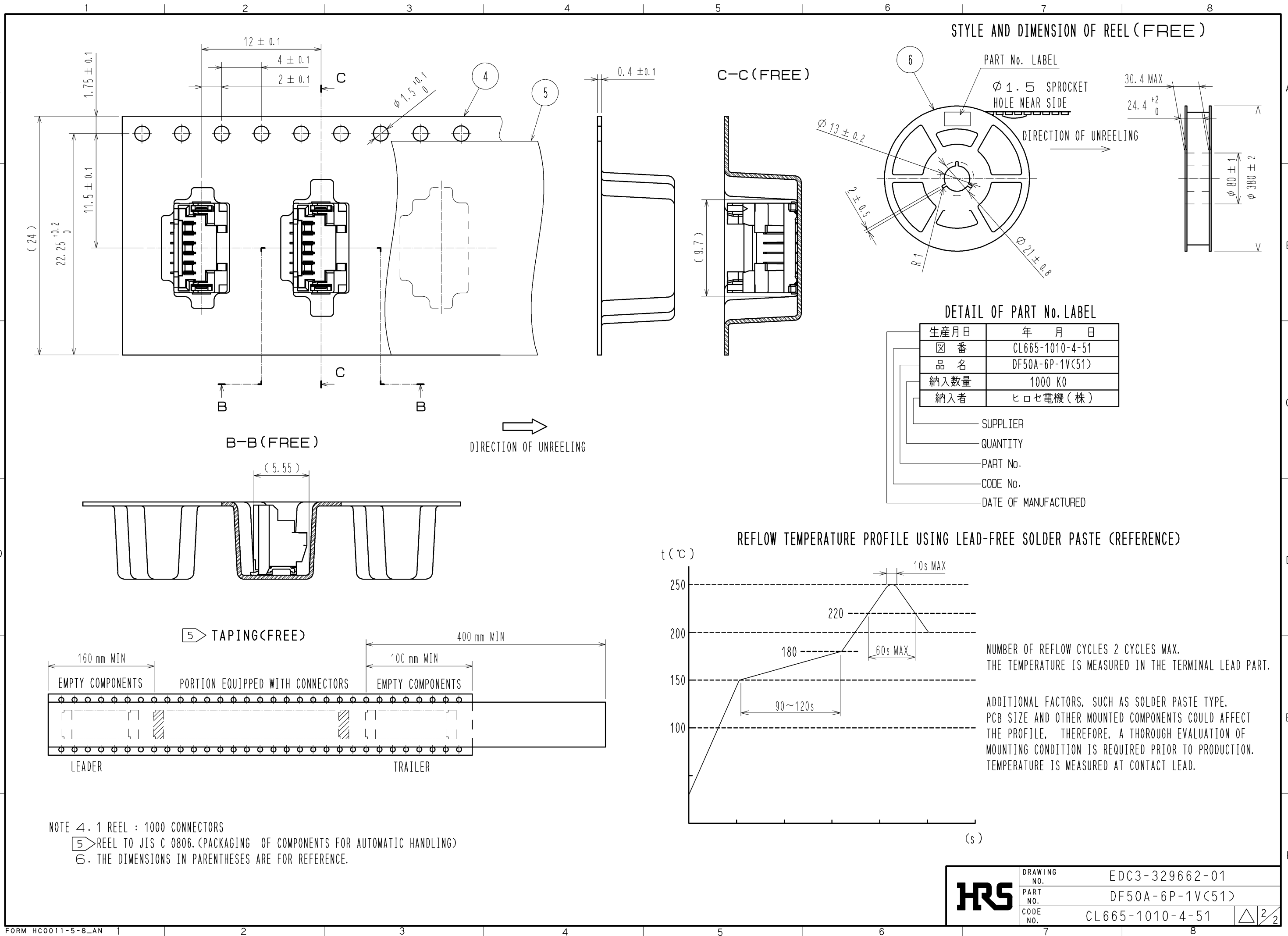
MATING FIGURE (5 : 1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
2. [Hatched Area] AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	PHOSPHOR BRONZE	CONTACT AREA : Sn PLATING 1μm MIN. UNDER PLATING : Cu PLATING 0.3μm MIN.	3	PS	REEL . BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN. LEAD AREA : Au PLATING 0.05μm MIN. UNDER PLATING : Ni PLATING 1μm MIN.	3	POLYESTER	CLEAR
1	LCP	BLACK , UL94V-0	3	PS	CLEAR
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS

UNITS mm		SCALE 5 : 1	COUNT △	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : KI. AKIYAMA 11.06.28				DRAWING NO. EDC3-329662-01			
CHECED : OM. MIYAMOTO 11.06.28				PART NO. DF50A-6P-1V(51)			
DESIGNED : TT. OHSAKO 11.06.28				CODE NO. CL665-1010-4-51			
DRAWN : ST. SATO 11.06.27				△ 1/2			



HRS	DRAWING NO.	EDC3-329662-01
	PART NO.	DF50A-6P-1V(51)
	CODE NO.	CL665-1010-4-51
		△ 2/2